

# 5G

## Introducing

### Advanced Millimeter Wave Multi-layer Materials

### RO4835T™ Laminates,

### RO4450T™ Bonding Materials,

### And CU4000™ & CU4000 LoPro® Foils

**Rogers Corporation Introduces [RO4835T™ Laminates](#), [RO4450T™ Bonding Materials](#), and [CU4000™ & CU4000 LoPro® Foils](#)**

Rogers Corporation is pleased to introduce a set of next generation products designed to meet the existing and emerging needs of advanced millimeter wave multi-layer designs.

RO4835T™ laminates, offered in a 2.5 mil, 3 mil and 4 mil core thickness, are 3.3 Dk, low loss, spread glass reinforced, ceramic filled thermoset materials designed for inner-layer use in multilayer board designs, and complement RO4835™ laminates when thinner cores are needed. Secondly, RO4450T™ Bonding Materials are 3.2-3.3 Dk, low loss, spread glass reinforced, ceramic filled bonding materials that were designed to complement RO4835T and the existing RO4000® laminate family, and come in 3 mil, 4 mil or 5 mil thicknesses. Lastly, CU4000™ and CU4000 LoPro® Foils are sheeted foil options for designers looking for foil lamination builds, and provide good outer layer adhesion when used with RO4000 products.

RO4835T laminates and RO4450T bonding materials exhibits excellent Dk control for repeatable electrical performance, a low z axis expansion for plated through hole reliability, and are compatible with standard epoxy/glass (FR-4) processes. These materials are an excellent choice for multilayer designs requiring sequential laminations, as fully cured RO4000 products are capable of withstanding multiple lamination cycles. RO4835T laminate and RO4450T bondply have the UL 94 V-0 flame retardant rating, and are compatible with lead-free processes.

